

Filename: PMP5236_REVB_bom.xls						
Date: 04/17/2014						
PMP5236_REVB BOM						
COUNT	RefDes	Value	Description	Size	Part Number	Mfr
4	C50, C52, C54, C56	18pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
2	C19, C39	47pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
2	C24, C44	100pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
2	C100, C101	220pF	Capacitor, Ceramic, 50V, C0G, 10%	603	Std	Std
2	C18, C38	330pF	Capacitor, Ceramic, 100V, C0G, 10%	603	Std	Std
2	C1, C4	1000pF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	Std
2	C23, C43	0.01uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
4	C5, C6, C7, C8	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	Std
2	C25, C45	0.033uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C26, C46	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C53, C57	1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
6	C10, C14, C29, C30, C34, C49	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	Std
4	C22, C28, C42, C48	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	Std	Std
2	C27, C47	2.2uF	Capacitor, Ceramic, 16V, X7R, 10%	805	Std	Std
2	C51, C55	22uF	Capacitor, Ceramic, 10V, X5R, 10%	805	Std	Std
4	C12, C13, C32, C33	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A225K	TDK
4	C15, C16, C35, C36	22uF	Capacitor, Ceramic, 16V, X5R, 20%	1210	Std	Std
3	C9, C20, C40	1000pF	Capacitor, Ceramic, 2KV, X7R, 10%	1812	C4532X7R3D102K	TDK
2	C21, C41	22uF	Capacitor, Aluminum, 16V, 20%	5x5.8mm	EEEFK1C220R	Panasonic
2	C17, C37	150uF	Capacitor, Aluminum, 16V, 20%	6.3x7.7mm	EEEFK1C151XP	Panasonic
2	C11, C31	47uF	Capacitor, Aluminum, 63V, ±20%	8x10.2mm	EEEFK1J470P	Panasonic
8	D1, D2, D4, D5, D6, D7, D9, D10		Diode, Schottky, 1A, 100V	SMA	B1100	Diodes, Inc
2	D11, D16		Diode, Rectifier, 1A, 200V	SMA	MURA120	On Semi
4	D12, D14, D17, D19		Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
2	D13, D18		Diode, Schottky, 7A, 60V	Power DI-5	PDS760	Diodes
2	D15, D20		Diode, Dual Schottky, 200mA, 30V	SOT23	BAT54S	Diodes, Inc
2	D3, D8		Diode, SMT TVS 400W, 4.3-A, 58-V	SMA	SMAJ58A	Diodes
4	FB1, FB2, FB3, FB4		Bead, Ferrite, SMT, 150 Ohms, 1.5A	805	MMZ2012R150A	TDK
2	J1, J2		Connector, Jack, Modular, 8 POS	0.705 x 0.820 inch	520252-4	AMP
6	J3, J4, J5, J6, J8, J9		Header, Male 2-pin, 100mil spacing,	0.100 inch x 2	PEC02SAAN	Sullins
1	J7		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25	ED1514	
2	L1, L3	3.3uH	Inductor, SMT, 1.53A, 32milliohm	5.1x5.1mm	MSS5131-332MX	Coilcraft
2	L2, L4	0.33uH	Inductor, SMT, 3A, 25 milliohm	3.9x3.9mm	LPS4012-331ML	Coilcraft

2	Q1, Q3		MOSFET, N-ch, 150V, 4.9A, 47 milliohm	SO8	FDS2572	Fairchild
2	Q2, Q4		Bipolar, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1	On Semi
4	R15, R21, R38, R44	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R60, R67	20	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R10, R33	20	Resistor, Chip, 1/16W, 5%	603	Std	Std
2	R29, R52	63.4	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R5, R6, R7, R8	75	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R19, R42, R55, R62	200	Resistor, Chip, 1/16W, 1%	603	Std	Std
6	R14, R37, R56, R58, R63, R65	1K	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R18, R20, R41, R43	2K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R28, R51	2.61K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R17, R40	3.01K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R31, R53	4.99K	Resistor, Chip, 1/16W, 1%	603	Std	Std
6	R16, R22, R23, R39, R45, R46	10K	Resistor, Chip, 1/16W, 1%	603	Std	Std
6	R24, R27, R30, R47, R50, R68	24.9K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R26, R49	69.8K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R25, R48	75K	Resistor, Chip, 1/16W, 1%	603	Std	Std
4	R57, R59, R64, R66	100K	Resistor, Chip, 1/16W, 1%	603	Std	Std
2	R12, R35	20	Resistor, Chip, 1/10W, 5%	805		std
4	R1, R2, R3, R4	0	Resistor, Chip, 1/4W, 5%	1206	Std	Std
2	R54, R61	0.025	Resistor, Chip, 1/4W, 1%	1206	Std	Std
2	R13, R36	0.25	Resistor, Chip, 1/2W, 1%	2010	Std	Std
2	R11, R34	24	Resistor, Chip, 1/2W, 5%	2010	Std	Std
2	R9, R32	39K	Resistor, Chip, 1W, 5%	2512	Std	Std
2	T1, T2		Transformer,	S0 14 Wide	ETH1-230LD	Coilcraft
2	T3, T4		Transformer, Flyback	0.810 X 1.181 inch	JA4387-AL	Coilcraft
1	TP1		Test Point, White, Thru Hole	0.125 x 0.125 inch	5012	Keystone
2	TP2, TP3		Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	U2, U6		IC, Photocoupler, 80-160% CTR	MF4	TCMT1107	Vishay
2	U4, U8		Photocoupler, 300-600% CTR, 3.75KV Isolation	MF4	PC357N4TJ00F	Sharp
2	U3, U7		IC, Shunt Regulator, 2.5V ref, 36V, 100mA, 1%	SOT23-5	TL431ACDBVR	Texas Instruments
2	U9, U10		IC, Load-Share Controller	SO-8	UCC29002D/1	Texas Instruments
2	U1, U5		IC, IEEE 802.3at PoE Interface/Isolated Converter Controller	PWP20	TPS23754PWP	Texas Instruments

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